

DA9142-A

High-Performance, 13 A/20 A Peak, DC-DC Converter

The DA9142-A is an Automotive grade, high efficiency, 13 A continuous and 20 A peak, dual-phase, DC-DC stepdown converter (buck). It is fully AEC-Q100 qualified.

With remote sensing, the DA9142-A improves output voltage regulation at the point of load.

Fully integrated switching FETs means no external FETs or Schottky diodes are needed.

A programmable soft startup can be enabled, which limits the inrush current from the input node and secures a slope-controlled rail activation.

The dynamic voltage control (DVC) supports adaptive adjustment of the supply voltage dependent on the processor load, via either a direct register write using the communication interface (I²C compatible) or with a programmable input pin.

A configurable GPI allows multiple I²C address selection for multiple instances of DA9142-A in the same application.

DA9142-A has integrated over-temperature and over-current protection for increased system reliability, without the need for external sensing components.

Key Features

- 2.8 V to 5.5 V input voltage
- 0.5 V to 1.3 V output voltage
- Up to 20 A peak output current, 13 A continuous output current
- 4 MHz nominal switching frequency
- Dual-phase operation
- 110 nH inductor per phase
- 110 µF output capacitor
- ±1% output voltage accuracy (static)
- ±5% load transient
- I²C-compatible interface (FM+)
- Programmable GPIOs
- Programmable soft startup
- Voltage, current, and temperature supervision
- Automotive Grade 1
- 60 FC-BGA 4.5 mm x 7 mm (0.65 mm pitch)
- 130 mm² total solution area
- AEC-Q100 qualified

Applications

- Navigation systems
- Telematics
- AI engines
- Automotive infotainment
- Advanced driver assistance systems (ADAS)
- SiPP modules

Contents

Key Features	1
Applications	1
Contents	2
Figures	3
Tables.....	3
1. Terms and Definitions	5
2. Overview	6
2.1 Block Diagram	6
3. Pin Information	7
3.1 Pin Assignments	7
3.2 Pin Descriptions	7
4. Specifications	9
4.1 Absolute Maximum Ratings	9
4.2 Electrostatic Discharge Ratings	9
4.3 Recommended Operating Conditions	9
4.4 Thermal Specifications	10
4.4.1 Power Derating Curves	10
4.5 Buck1 Characteristics	11
4.6 Performance and Supervision Characteristics	13
4.7 Digital IO Characteristics	13
4.8 Timing Characteristics	14
5. Typical Performance	15
6. Functional Description	16
6.1 Operating Modes	16
6.1.1 ON	16
6.1.2 OFF	16
6.2 DC-DC Buck Converter	16
6.2.1 Switching Frequency	16
6.2.2 Operation Modes and Phase Selection	16
6.2.3 Output Voltage Selection	17
6.2.4 Soft Startup and Shutdown	17
6.2.5 Current Limit	17
6.2.6 Temperature Protection	17
6.3 Control Circuits	19
6.3.1 Chip Enable and Disable	19
6.3.2 GPIO	19
6.3.3 Interrupt	21
6.4 I ² C Communication	23
6.4.1 I ² C Protocol	23
7. Register Definitions	25
7.1 Register Map	25

7.2	Register Descriptions.....	27
7.2.1	System	27
7.2.2	Buck1	36
7.2.3	OTP Control	40
8.	Moisture Sensitivity Level.....	41
8.1	Soldering Information.....	41
9.	Package Outline Drawings.....	42
9.1	Package Outline	42
9.2	Package Marking.....	43
10.	Ordering Information.....	44
10.1	Variants Ordering Information	44
11.	Application Information	45
11.1	Capacitor Selection.....	45
11.2	Inductor Selection	45
12.	Layout Guidelines.....	46

Figures

Figure 1.	Block Diagram	6
Figure 2.	Pinout Diagram (Top View)	7
Figure 3.	Power Derating Curve	10
Figure 4.	DA9142-A Efficiency, PWM Mode without Phase Shedding	15
Figure 5.	DA9142-A Efficiency, Auto Mode with Phase Shedding	15
Figure 6.	Buck Output Voltage Control Concept	17
Figure 7.	Temperature Protection Operation	18
Figure 8.	Interrupt Operation Example	22
Figure 9.	I ² C START and STOP Condition Timing	23
Figure 10.	I ² C Byte Write (SDA Line)	23
Figure 11.	I ² C Byte Read (SDA Line) Examples	24
Figure 12.	Package Outline Drawing	42
Figure 13.	Chip Marking Details	43
Figure 14.	DA9142-A Footprint.....	46

Tables

Table 1.	Pin Description.....	7
Table 2.	Pin Type Definition.....	8
Table 3.	Absolute Maximum Ratings	9
Table 4.	Electrostatic Discharge Ratings.....	9
Table 5.	Recommended Operating Conditions	9
Table 6.	Package Ratings.....	10
Table 7.	Typical Temperatures	10
Table 8.	Dual-Phase Buck Electrical Characteristics	11
Table 9.	Performance and Supervision Electrical Characteristics.....	13
Table 10.	Digital I/O Electrical Characteristics	13
Table 11.	I ² C Electrical Characteristics.....	14

Table 12. Temperature Protection Control Registers	18
Table 13. GPIO Pin Assignment	19
Table 14. GPIO0 Configurable Registers when CONF Enabled	19
Table 15. Interrupt List	21
Table 16. Interrupt Registers Except for Power-Good Status	22
Table 17. Interrupt Registers for Power-Good and Temperature Warning Status	22
Table 18: Register Map	25
Table 19: SYS_STATUS_0 (0x01)	27
Table 20: SYS_STATUS_1 (0x02)	27
Table 21: SYS_STATUS_2 (0x03)	27
Table 22: SYS_EVENT_0 (0x04)	27
Table 23: SYS_EVENT_1 (0x05)	27
Table 24: SYS_EVENT_2 (0x06)	27
Table 25: SYS_MASK_0 (0x07)	28
Table 26: SYS_MASK_1 (0x08)	28
Table 27: SYS_MASK_2 (0x09)	28
Table 28: SYS_MASK_3 (0x0A)	28
Table 29: SYS_CONFIG_2 (0x0D)	28
Table 30: SYS_CONFIG_3 (0x0E)	29
Table 31: SYS_GPIO0_0 (0x10)	29
Table 32: SYS_GPIO0_1 (0x11)	30
Table 33: SYS_GPIO1_0 (0x12)	31
Table 34: SYS_GPIO1_1 (0x13)	31
Table 35: SYS_GPIO2_0 (0x14)	32
Table 36: SYS_GPIO2_1 (0x15)	33
Table 37: SYS_GPIO3_0 (0x16)	33
Table 38: SYS_GPIO3_1 (0x17)	34
Table 39: SYS_GPIO4_0 (0x18)	35
Table 40: SYS_GPIO4_1 (0x19)	35
Table 41: SYS_CFG_SLVADDR (0xA1)	36
Table 42: BUCK_BUCK1_0 (0x20)	36
Table 43: BUCK_BUCK1_1 (0x21)	37
Table 44: BUCK_BUCK1_2 (0x22)	37
Table 45: BUCK_BUCK1_3 (0x23)	38
Table 46: BUCK_BUCK1_4 (0x24)	38
Table 47: BUCK_BUCK1_5 (0x25)	39
Table 48: BUCK_BUCK1_6 (0x26)	39
Table 49: BUCK_BUCK1_7 (0x27)	40
Table 50: OTP_DEVICE_ID (0x48)	40
Table 51: OTP_VARIANT_ID (0x49)	40
Table 52: OTP_CUSTOMER_ID (0x4A)	40
Table 53: OTP_CONFIG_ID (0x4B)	40
Table 54. MSL Classification	41
Table 55. Ordering Information for Consumer/Industrial Applications	44
Table 56. Ordering Information for Automotive Applications	44
Table 57: Recommended Automotive-Grade Capacitor Types	45
Table 58: Recommended Inductor Types	45

1. Terms and Definitions

CPU	Central processing unit
DDR	Dual data rate
DVC	Dynamic voltage control
FET	Field effect transistor
FM+	Fast mode plus
GPI	General purpose input
GPIO	General purpose input/output
GPU	Graphics processing unit
IC	Integrated circuit
OTP	One time programmable
PCB	Printed circuit board
SCL	Serial clock
SDA	Serial data
SIPP	Single in-line pin package

2. Overview

2.1 Block Diagram

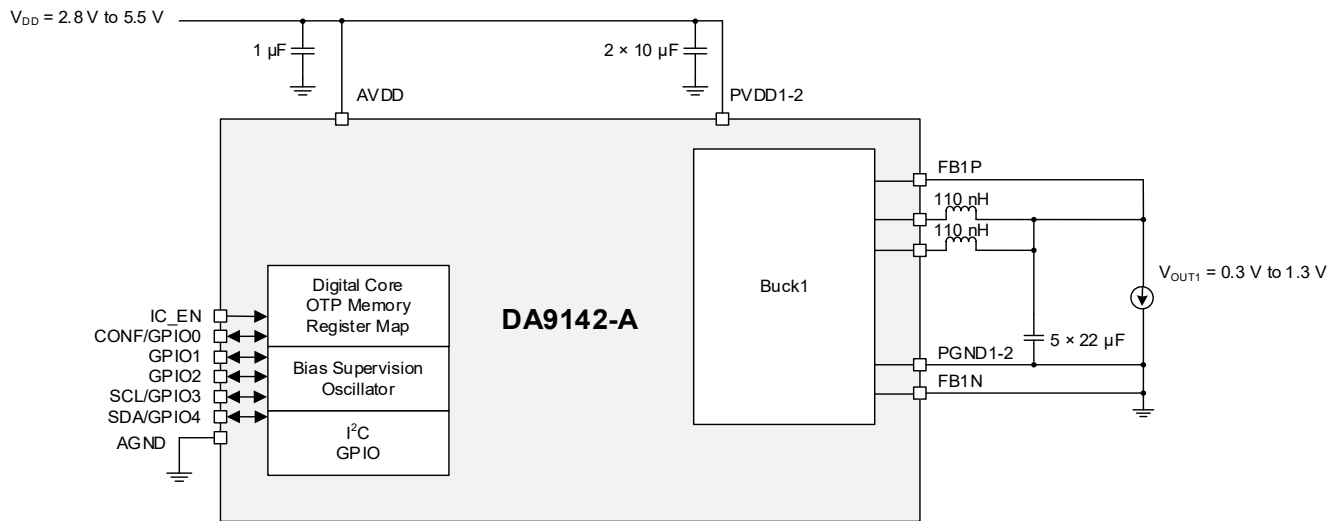


Figure 1. Block Diagram

3. Pin Information

3.1 Pin Assignments

	1	2	3	4	5	6
A	PVDD1	LX1	PGND1	PGND2	LX2	PVDD2
B	PVDD1	LX1	PGND1	PGND2	LX2	PVDD2
C	PVDD1	LX1	PGND1	PGND2	LX2	PVDD2
D	PVDD1	LX1	PGND1	PGND2	LX2	PVDD2
E	GPIO1	GPIO2	AGND	FBP	AVDD	SCL/ GPIO3
F	CONF/ GPIO0	AGND	IC_EN	FBN	AVDD	SDA/ GPIO4
G	PVDD3	LX3	PGND3	PGND4	LX4	PVDD4
H	PVDD3	LX3	PGND3	PGND4	LX4	PVDD4
J	PVDD3	LX3	PGND3	PGND4	LX4	PVDD4
K	PVDD3	LX3	PGND3	PGND4	LX4	PVDD4

Top view

 High Power, Noisy	 Analog signal, Sensitive	 Quasi-static digital signal	 No connection
 High Power	 Digital signal. Noisy	 Noisy ground	 Quiet ground

Figure 2. Pinout Diagram (Top View)

3.2 Pin Descriptions

Table 1. Pin Description

Pin Number	Pin Name	Type (Table 2)	Drive (mA)	Description
A1, B1, C1, D1	PVDD1	PWR	10000	Supply voltage for buck power stage, decouple with 10 μ F and connect to same source as AVDD
A2, B2, C2, D2	LX1	AIO	10000	Switch node of buck, connect a 100 nH inductor between LX1 and output capacitor

Pin Number	Pin Name	Type (Table 2)	Drive (mA)	Description
A3, B3, C3, D3	PGND1	GND	10000	Buck power stage GND
A4, B4, C4, D4	PGND2	GND	10000	Buck power stage GND
A5, B5, C5, D5	LX2	AIO	10000	Switch node of buck, connect a 100 nH inductor between LX2 and output capacitor
A6, B6, C6, D6	PVDD2	PWR	10000	Supply voltage for buck power stage, decouple with 10 μ F and connect to same source as AVDD
E1	GPIO1	DIO	10	General purpose I/O
E2	GPIO2	DIO	10	General purpose I/O
E3, F2	AGND	GND	10	Analog control and auxiliary circuitry GND
E4	FBP	AI	10	Buck positive node of differential voltage feedback, connect to VOUT1 at point of load
E5, F5	AVDD	PWR	10	Supply rail for analog control circuitry, decouple with 1 μ F and connect to same source as PVDD
E6	SCL/GPIO3	DIO	15	I ² C clock or general purpose I/O
F1	CONF/GPIO0	AI/DIO	10	Chip configuration or general purpose I/O
F3	IC_EN	AI	10	Powers up I ² C control interface and auxiliary circuitry (including bandgap, oscillator, and references)
F4	FBN	AI	10	Buck negative node of differential voltage feedback, connect to GND at point of load
F6	SDA/GPIO4	DIO	15	I ² C data or general purpose I/O
G1, H1, J1, K1	PVDD3	PWR	10000	Supply voltage for buck power stage, connect to same source as AVDD
G2, H2, J2, K2	LX3	AIO	0	Do Not Connect
G3, H3, J3, K3	PGND3	GND	10000	Buck power stage VSS rail
G4, H4, J4, K4	PGND4	GND	10000	Buck power stage VSS rail
G5, H5, J5, K5	LX4	AIO	0	Do Not Connect
G6, H6, J6, K6	PVDD4	PWR	10000	Supply voltage for buck power stage, connect to same source as AVDD

Table 2. Pin Type Definition

Pin Type	Description	Pin Type	Description
DI	Digital input	AI	Analog input
DO	Digital output	AO	Analog output
DIO	Digital input/output	AIO	Analog input/output
PWR	Power	GND	Ground

4. Specifications

4.1 Absolute Maximum Ratings

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, so functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification are not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions can adversely impact product reliability and result in failures not covered by warranty.

Table 3. Absolute Maximum Ratings

Parameter	Description	Conditions	Min	Max	Unit
T _{STG}	Storage temperature		-65	150	°C
T _J	Junction temperature		-40	150	°C
V _{SYS}	System supply voltage		-0.3	6.0	V
V _{PIN}	Voltage on pins		-0.3	6.0	V

4.2 Electrostatic Discharge Ratings

Table 4. Electrostatic Discharge Ratings

Parameter	Description	Conditions	Rating	Unit
V _{ESD_HBM}	Maximum ESD protection	Human body model (HBM) All exposed pins	2	kV
V _{ESD_CDM}	Maximum ESD protection	Charged device model (CDM)	500 Note 1	V

Note 1 Increased to 750 V for corner balls.

4.3 Recommended Operating Conditions

Table 5. Recommended Operating Conditions

Parameter	Description	Conditions	Min	Typ	Max	Unit
V _{SYS}	System supply voltage		2.8		5.5	V
V _{PIN}	Voltage on pins		-0.3		V _{SYS} + 0.3	V
T _J	Junction temperature		-40		150	°C
T _A	Ambient temperature		-40		125	°C

4.4 Thermal Specifications

Table 6. Package Ratings

Parameter	Description	Conditions	Min	Typ	Max	Unit
θ_{JA}	Thermal resistance junction to ambient	No heatsink Note 1		16.4		°C/W
		With heatsink Note 2		9.6		°C/W
θ_{JB}	Thermal resistance junction to board	Note 1		9.2		°C/W
θ_{JC}	Thermal resistance junction to case	Note 1		7.0		°C/W
P_D	Maximum power dissipation	No heatsink Derating factor above $T_A = 85^\circ\text{C}$: $60.9 \text{ mW}/^\circ\text{C}$ ($1/\theta_{JA}$)	3660	4270		mW
		With heatsink Derating factor above $T_A = 85^\circ\text{C}$: $104.1 \text{ mW}/^\circ\text{C}$ ($1/\theta_{JA}$)	6250	7290		mW

Note 1 Obtained from package thermal simulations, JEDEC 2S2P four-layer board (114.3 mm x 101.6 mm x 1.6 mm), 70 μm (2 oz) copper thickness power planes, 35 μm (1 oz) copper thickness signal layer traces, natural convection (still air)

Note 2 As per [Note 1](#) with addition of aluminum heatsink, 114.3 mm x 101.6 mm x 1.0 mm representing the lid of a case.

4.4.1 Power Derating Curves

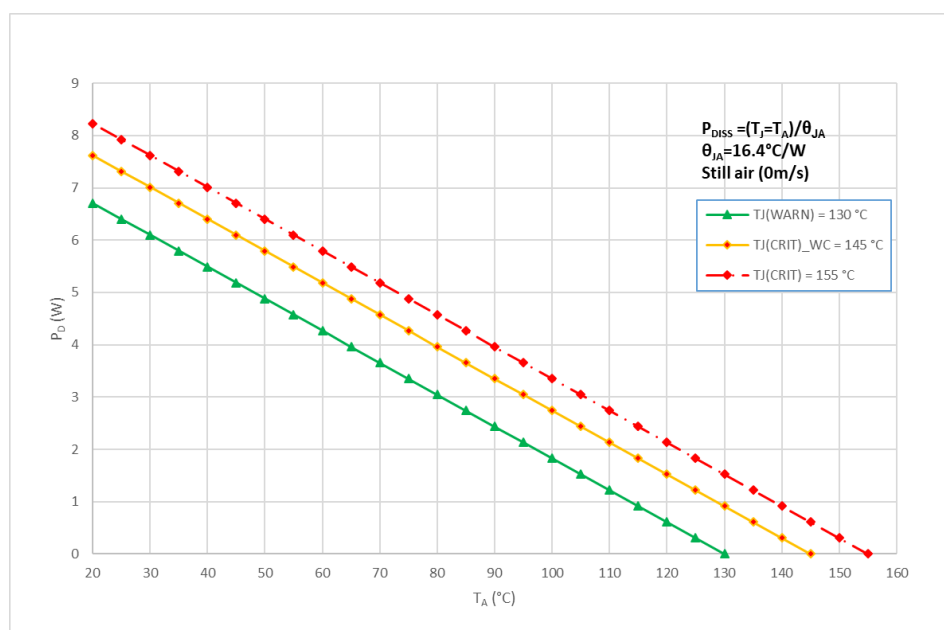


Figure 3. Power Derating Curve

Table 7. Typical Temperatures

	$T_A = 85^\circ\text{C}$	$T_A = 105^\circ\text{C}$	$T_A = 125^\circ\text{C}$
T_{J_WARN}	$P_D = 2.74 \text{ W}$	$P_D = 1.52 \text{ W}$	$P_D = 0.30 \text{ W}$
$T_{J_CRIT_WC}$	$P_D = 3.66 \text{ W}$	$P_D = 2.44 \text{ W}$	$P_D = 1.22 \text{ W}$

4.5 Buck1 Characteristics

Unless otherwise noted, the following is valid for $T_J = -40\text{ }^{\circ}\text{C}$ to $+150\text{ }^{\circ}\text{C}$, $V_{SYS} = 2.8\text{ V}$ to 5.5 V .

Table 8: Dual-Phase Buck Electrical Characteristics

Parameter	Description	Conditions	Min	Typ	Max	Unit
External electrical conditions						
V_{IN}	Input voltage	$V_{IN} = V_{SYS} = V_{AVDD}$	2.8		5.5	V
C_{OUT}	Total output capacitance, including voltage and temperature coefficient	Typ $8 \times 22\text{ }\mu\text{F}$ -40% to +20%	106	176	211	μF
ESR_{COUT}	Output capacitor series resistance, per capacitor	$f > 100\text{ kHz}$		3		m Ω
L	Inductor value, per phase, including current and temperature dependence		88	110	132	nH
DCR_L	Inductor DC resistance			2		m Ω
Electrical performance						
V_{OUT}	Output voltage, configurable in 10 mV steps	$I_{OUT} = 0\text{ mA}$ to $I_{OUT_MAX_PK}$ $V_{IN} = 2.8\text{ V}$ to 5.5 V	0.5	0.85	1.3	V
V_{OUT_ACC}	Output voltage accuracy, including static line and load regulation		-10		10	mV
V_{OUT_ACC}	Output voltage accuracy, including static line and load regulation	$V_{OUT} \geq 1\text{ V}$	-1		1	%
$I_{OUT_MAX_CONT}$	Maximum continuous output current	With suitable thermal design	13			A
$I_{OUT_MAX_PK}$	Maximum peak output current	With suitable thermal design	20			A
I_{LIM}	Current limit, configureable per phase Note 1 Note 2			14.5		A
I_{LIM_ACC}	Current limit accuracy Note 2		-20		20	%
$V_{THR_PG_HYS}$	Power-good voltage threshold hysteresis	$V_{OUT} = V_{THR_PG_DWN}$	70	80	90	mV
$V_{THR_PG_DWN}$	Power-good voltage threshold for falling	$V_{OUT} = V_{BUCK}$	-170	-140	-110	mV
V_{THR_HV}	High V_{OUT} voltage threshold	$V_{OUT} = V_{BUCK}$	130	160	195	mV
$V_{OUT_TR_LINE}$	Line transient response	$V_{IN} = 3.0\text{ V}$ to 3.6 V $V_{OUT} = 1.1\text{ V}$ $I_{OUT} = 0.5 \times I_{OUT_MAX_PK}$ $dt = 10\text{ }\mu\text{s}$		10		mV

Parameter	Description	Conditions	Min	Typ	Max	Unit
f_{SW}	Switching frequency			4		MHz
t_{ON_MIN}	Minimum turn-on pulse 0% duty is also supported			10		ns
t_{BUCK_EN}	Turn-on time	CH1_EN = high $V_{IN} = 3.3\text{ V}$ $V_{OUT} = 0.85\text{ V}$ DVC slew rate: 10 mV/8 μ s No load Recommended capacitance		600		μ s
R_{PD}	Output pull-down resistance for each phase at the LX node, see CH1_PD_DIS	$V_{IN} = 3.3\text{ V}$ $V_{OUT} = 0.5\text{ V}$	140	150	160	Ω
R_{ON_PMOS}	On resistance of switching PMOS, per phase	$V_{IN} = 3.3\text{ V}$		12		m Ω
R_{ON_NMOS}	On resistance of switching NMOS, per phase	$V_{IN} = 3.3\text{ V}$		6		m Ω
PWM Mode						
η_{PWM}	Efficiency, PWM	$V_{IN} = 3.3\text{ V}$ $V_{OUT} = 1.1\text{ V}$ $I_{OUT} = 5\% (I_{OUT_MAX_PK})$ to 80% ($I_{OUT_MAX_PK}$)		80		%
AUTO Mode						
$V_{OUT_TR_LD_RISE}$	Load transient response, phase shedding enabled	$V_{OUT} = 1.1\text{ V}$ $I_{OUT} = 25\%$ to 75% of $I_{OUT_MAX_PK}$ Load rise time = 1 μ s	-5			%
$V_{OUT_TR_LD_FALL}$	Load transient response, phase shedding enabled	$V_{OUT} = 1.1\text{ V}$ $I_{OUT} = 75\%$ to 25% of $I_{OUT_MAX_PK}$ Load fall time = 1 μ s			5	%
PFM Mode						
$I_{Q_PFM_1PH}$	Quiescent current in PFM	$V_{IN} = 3.3\text{ V}$ No load No switching		120		μ A
η_{PFM}	Efficiency, PFM	$V_{IN} = 3.3\text{ V}$ $V_{OUT} = 1.1\text{ V}$ $I_{OUT} = 100\text{ mA}$		80		%

Note 1 For applications requiring $V_{OUT} < 0.75\text{ V}$ contact Renesas applications support for configuration setting

Note 2 $t_{ON} > 40\text{ ns}$

4.6 Performance and Supervision Characteristics

Table 9: Performance and Supervision Electrical Characteristics

Parameter	Description	Conditions	Min	Typ	Max	Unit
Electrical performance						
V _{THR_POR}	Power-on-reset threshold	Threshold for AVDD falling		2.1	2.25	V
V _{THR_POR_HYS}	Power-on-reset hysteresis			200		mV
T _{WARN}	Temperature warning threshold		120	130	140	°C
T _{CRIT}	Temperature shutdown threshold		145	155	165	°C
I _{IN_OFF}	Supply current	OFF state T _A = 27 °C IC_EN = 0		0.1	1	μA
I _{IN_ON}	Supply current	ON state T _A = 27 °C IC_EN = 1 Buck off	5	10	20	μA

4.7 Digital IO Characteristics

Table 10: Digital I/O Electrical Characteristics

Parameter	Description	Conditions	Min	Typ	Max	Unit
Electrical performance						
V _{IH_EN}	Input high voltage, IC enable		1.2		AVDD	V
V _{IL_EN}	Input low voltage, IC enable				0.4	V
t _{IC_EN}	IC enable time				1000	μs
V _{IH_GPIO_SCL_SDA}	Input high voltage GPIO, SCL, SDA		1.2		AVDD	V
V _{IL_GPIO_SCL_SDA}	Input low voltage GPIO, SCL, SDA				0.4	V
V _{OH_GPIO}	Output high voltage GPIO	Push-pull mode I _{OUT} = 1 mA	0.8*AVDD		AVDD	V
V _{OL_GPIO}	Output low voltage GPIO	Push-pull mode I _{OUT} = 1 mA			0.2*AVDD	V
V _{OL_SDA}	Output low voltage SDA	I _{OUT} = 3 mA		0.24		V
R _{PD}	GPIO pull-down resistor	V _{SYS} = 3.7 V Note 1	9	15	31	kΩ
R _{PU}	GPIO pull-up resistor	V _{SYS} = 3.7 V Note 1	28	45	72	kΩ

Note 1 Resistance may have greater variation, depending on voltage and temperature.

4.8 Timing Characteristics

Table 11: I2C Electrical Characteristics

Parameter	Description	Conditions	Min	Typ	Max	Unit
Electrical performance						
t_{BUS}	Bus free time between a STOP and START condition		0.5			μs
C_{BUS}	Bus line capacitive load				150	pF
f_{SCL}	SCL clock frequency		20 Note 1		1000	kHz
t_{LO_SCL}	SCL low time		0.5			μs
t_{HI_SCL}	SCL high time		0.26			μs
t_{RISE}	SCL and SDA rise time	Requirement for input			1000	ns
t_{FALL}	SCL and SDA fall time	Requirement for input			300	ns
t_{SETUP_START}	Start condition setup time		0.26			μs
t_{HOLD_START}	Start condition hold time		0.26			μs
t_{SETUP_STOP}	Stop condition setup time		0.26			μs
t_{DATA}	Data valid time				0.45	μs
t_{DATA_ACK}	Data valid acknowledge time				0.45	μs
t_{SETUP_DATA}	Data setup time		50			ns
t_{HOLD_DATA}	Data hold time		0			ns

Note 1 Minimum clock frequency is limited to 20 kHz if I2C_TIMEOUT is enabled

5. Typical Performance

The static efficiency measurement plots depicted in Figure 4 and Figure 5 were performed at 25°C in a temperature-controlled environment. A continuous load was used for the measurements.

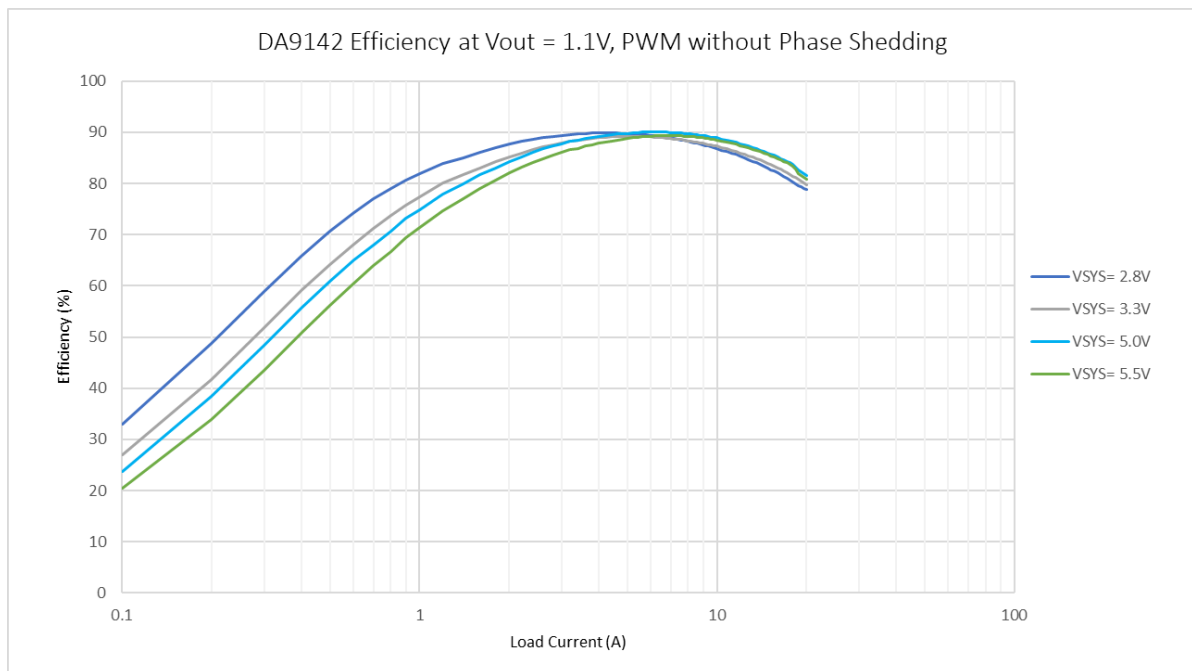


Figure 4. DA9142-A Efficiency, PWM Mode without Phase Shedding

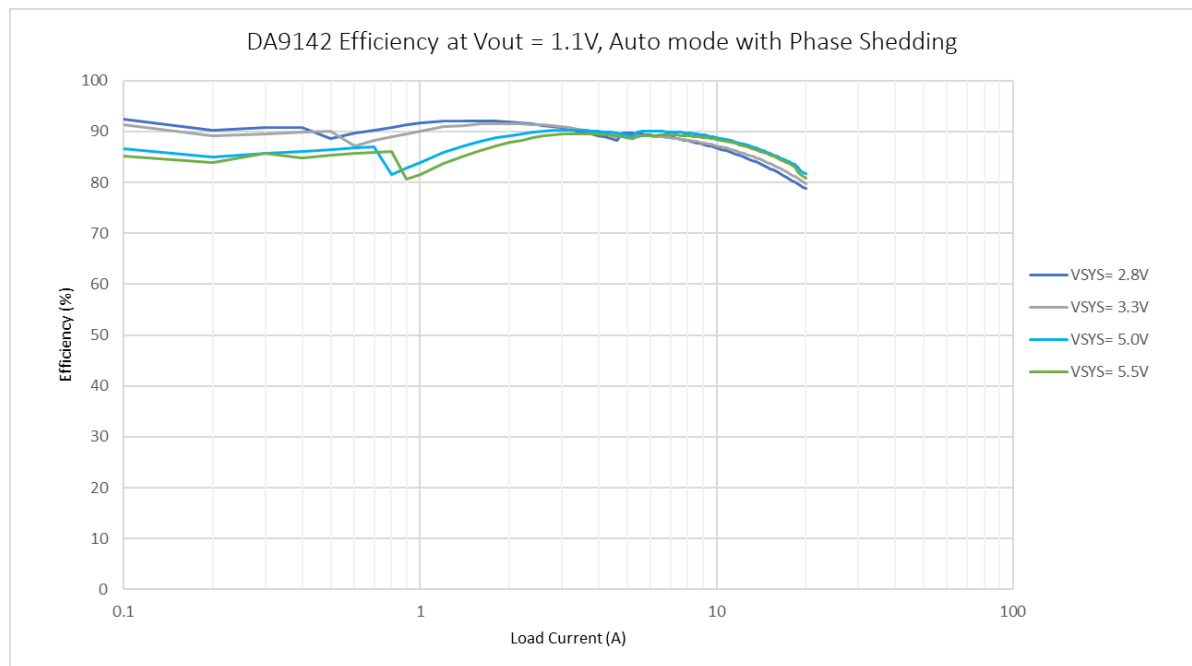


Figure 5. DA9142-A Efficiency, Auto Mode with Phase Shedding

6. Functional Description

6.1 Operating Modes

6.1.1 ON

DA9142-A is ON when the IC_EN pin is higher than V_{IH_EN} and the supply voltage is higher than V_{THR_POR} . Once enabled, the host processor can start communicating with DA9142-A using the control interface, after the t_{IC_EN} delay.

6.1.2 OFF

DA9142-A is OFF when the IC_EN pin is lower than V_{IL_EN} . In OFF, the buck is always disabled and the LX nodes are pulled down by a (typically 150 Ω) internal pull-down resistor.

6.2 DC-DC Buck Converter

DA9142-A operates as a single-channel, dual-phase buck converter which delivers up to 20 A output current at a 0.5 V to 1.3 V output voltage range.

The buck converter has two configurable output voltage settings. One is the normal output voltage (A), the other offers an alternative retention voltage (B). The bits used to configure the outputs are CH1_A_VOUT and CH1_B_VOUT. In this way, different application power modes are supported. The target output voltage (either A or B) is toggled by either GPI or I²C control interface, providing maximum flexibility for the application's host processor.

When the buck is enabled, its output voltage is monitored and a power-good signal indicates that the buck output voltage has reached a level higher than the power-good rise threshold. The power-good status is lost when the voltage drops below $V_{THR_PG_DWN}$ or increases above V_{THR_HV} . $V_{THR_PG_HYS}$ is the value that defines the hysteresis between a power-good rise and $V_{THR_PG_DWN}$. The status of the power-good indicator is read back via I²C from the PG1 status bit. Alternatively, it can be assigned to any of the GPIOs by setting the GPIO<x>_MODE bits to PG1 output.

The buck converter is capable of supporting DVC transitions that occur when:

- the active and selected A- or B-voltage is updated to a new target value, using bits CH1_A_VOUT and CH1_B_VOUT
- the voltage selection is toggled from the A- to B-voltage (or B- to A-voltage), using bit CH1_VSEL or via GPI control

The DVC operates in pulse-width-modulation (PWM) mode with synchronous rectification. The slew rate of the DVC ramp up and ramp down transitions is programmed at 10 mV per (8, 4, 2, 1, or 0.5) μ s in register bits CH1_SR_DVC_DWN and CH1_SR_DVC_UP.

A pull-down resistor (typically 150 Ω) for each phase is always activated when the buck is disabled, unless it is disabled by setting register bits CH1_PD_DIS to 0x1.

6.2.1 Switching Frequency

The buck switching frequency is tuned using register bit OSC_TUNE. The internal 8 MHz oscillator frequency is tuned in ± 160 kHz steps. This impacts the buck converter frequency in steps of 80 kHz and helps to mitigate possible disturbances to other high frequency systems in the application.

6.2.2 Operation Modes and Phase Selection

The buck converter operates in PWM or PFM modes. The operating mode is selected using register bits CH1_A_MODE and CH1_B_MODE.

Phase shedding automatically changes between 1- and 2-phase operation at a typical current of 4 A.

If the automatic operation mode (Auto mode) is selected, the buck converter automatically changes between synchronous PWM mode and PFM mode depending on the load current. This improves the efficiency across the range of output load currents.

6.2.3 Output Voltage Selection

The switching converter is configured using the I²C interface.

Two output voltages (Value A and Value B in Figure 6) are pre-configured in registers CH1_A_VOUT and CH1_B_VOUT. The output voltage (VBUCK in Figure 6) is selected by toggling register bit CH1_VSEL, by re-programming the selected voltage control register, or by toggling a GPI if configured to do so. Any of these options will result in ramped voltage transitions.

After being enabled, the buck converter uses, by default, the register settings in CH1_A_VOUT (Value A) unless the output voltage selection is configured via the GPI port to be CH1_B_VOUT.

Register bits CH1_VMAX limit the output voltage that can be set.

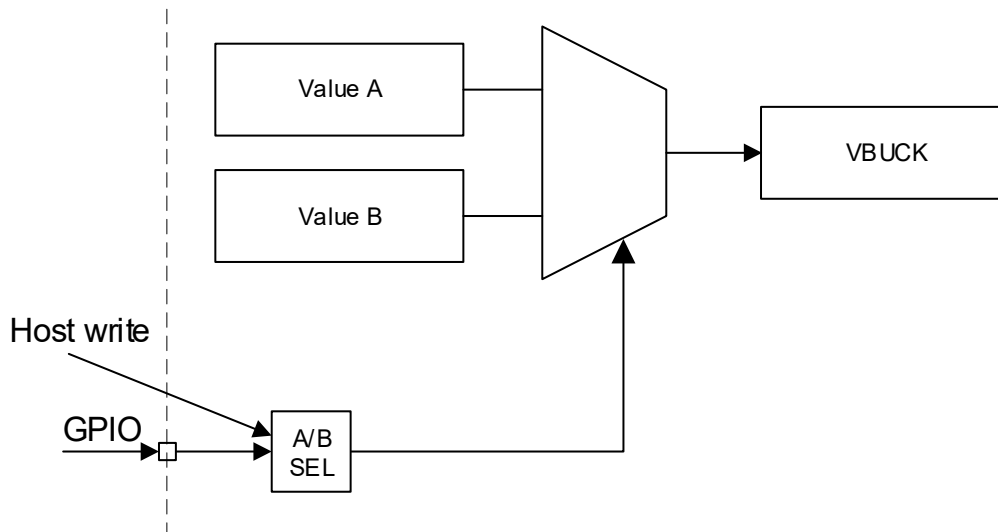


Figure 6. Buck Output Voltage Control Concept

6.2.4 Soft Startup and Shutdown

To limit in-rush current from VSYS, the buck converter performs a soft-start after being enabled. The startup behavior is a compromise between acceptable inrush current from the battery and turn-on time. Ramp times are configured in register CH1_SR_STARTUP.

Note: Rates higher than 5 mV/μs may produce overshoot during the startup phase.

A ramped power down is selected in register bits CH1_SR_SHDN. When no ramp is selected (immediate power down), the output node is discharged only by the pull-down resistor, if enabled, in register CH1_PD_DIS.

6.2.5 Current Limit

The integrated current limit protects the power stages and external coil from excessive current. It should be configured to at least 40% higher than the required maximum per phase output current.

Note: This value is loaded from the OTP.

When the current limit is reached, the buck converter generates an event and an interrupt to the host processor unless the interrupt has been masked using bit M_OC1 in SYS_MASK_1. Register bit OC_DVC_MASK masks over-current events during DVC transitions.

6.2.6 Temperature Protection

DA9142-A is protected from internal overheating by temperature-triggered shutdown.

DA9142-A uses two flags for temperature protection. When $T_J > T_{WARN}$, meaning that the chip is running close to its thermal limits, an IRQ is raised and an event is set, although the chip continues working.

When $T_J > T_{CRIT}$, another IRQ and event are set, and the bucks are immediately shut down. T_J needs to be below T_{WARN} and the event flags need to be cleared before starting the bucks.

Table 12. Temperature Protection Control Registers

Category	Register name	Description
Status	TEMP_WARN	Asserts when the temperature warning threshold is reached
	TEMP_CRIT	Asserts when the temperature shutdown threshold is reached
IRQ event	E_TEMP_WARN	TEMP_WARN caused event
	E_TEMP_CRIT	TEMP_CRIT caused event
IRQ mask	M_TEMP_WARN	TEMP_WARN event IRQ mask
	M_TEMP_CRIT	TEMP_CRIT event IRQ mask
	M_VR_HOT	TEMP_WARN status IRQ mask

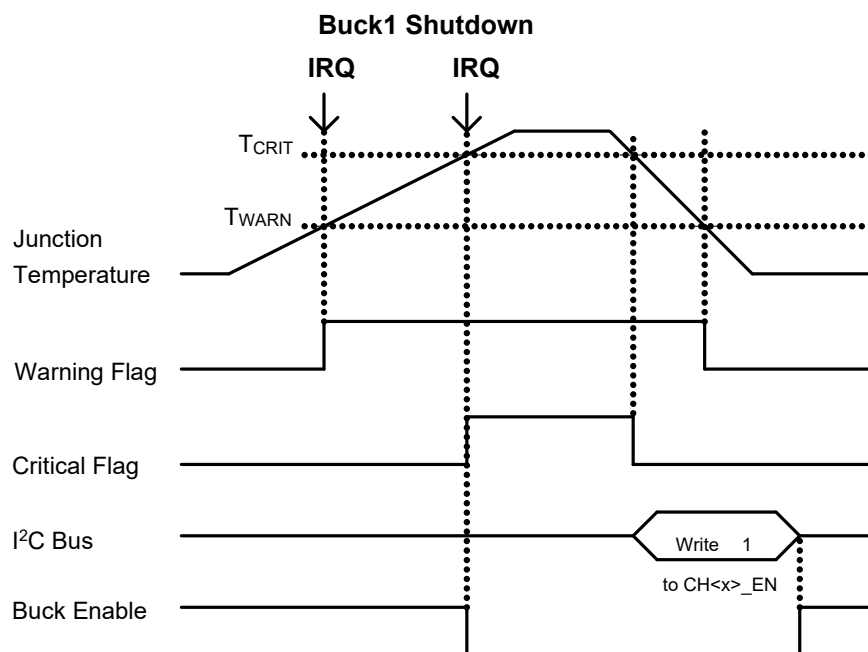


Figure 7. Temperature Protection Operation

6.3 Control Circuits

6.3.1 Chip Enable and Disable

The IC_EN pin enables and disables the IC. When IC_EN = 0, all blocks, except for low I_Q POR, power down and the buck output is pulled down.

6.3.2 GPIO

6.3.2.1 GPIO Pin Assignment

The DA9142-A provides up to five GPIO pins, three if the I²C is enabled, see [Table 13](#). The registers that configure the GPIO pin assignments are OTP programmable.

GPIO0 can be programmed (OTP option) to function as chip configuration (CONF), see section [6.3.2.3](#). When the I²C interface is enabled (OTP option) any register settings for GPIO3 and GPIO4 are ignored and GPIO3 and GPIO4 function as SCL and SDA respectively.

Note: GPIO3 and GPIO4 functions are limited only to output features if I2C_EN = 0.

Table 13. GPIO Pin Assignment

OTP Option		GPIO Pin					Available GPIOs
I ² C	CONF	CONF/ GPIO0	GPIO1	GPIO2	SCL/ GPIO3	SDA/ GPIO4	
Disabled	Disabled	GPIO0	GPIO1	GPIO2	GPIO3	GPIO4	5
	Enabled	CONF	GPIO1	GPIO2	GPIO3	GPIO4	4
Enabled	Disabled	GPIO0	GPIO1	GPIO2	SCL	SDA	3
	Enabled	CONF	GPIO1	GPIO2	SCL	SDA	2

6.3.2.2 GPIO Function

The GPIO pins are configurable as the following functions in register GPIO<x>_MODE (x = 0 to 4):

- Buck1 enable input (EN1)
- Buck1 DVC control input (DVC1)
- Buck1 OTP setting reload input (RELOAD)
- Buck1 power-good output (PG1)
- Interrupt output (nIRQ)

6.3.2.3 Chip Configuration Select

GPIO0 functions as chip configuration select (CONF) input when enabled as an OTP setting.

Three different chip configurations can be selected according to the CONF pin level.

- GPIO0 low: OTP default or CONF0 on reload
- GPIO0 high: CONF1
- GPIO0 floating: CONF2 - not recommended.

[Table 14](#) lists the device configurations that can be modified if CONF_EN = 1. Register CONF_EN is set by OTP, see section [10.1](#).

Table 14. GPIO0 Configurable Registers when CONF Enabled

Register Name	Description
IF_SLAVE_ADDR[6:0]	I ² C slave address
CH1_A_MODE[1:0]	CH1_A Operation mode select
CH1_B_MODE[1:0]	CH1_B Operation mode select
CH1_VSEL	CH1 output voltage and operation selection

Register Name	Description
CH1_EN	CH1 enable
CH1_A_VOUT[7:0]	CH1 output voltage setting A
CH1_B_VOUT[7:0]	CH1 output voltage setting B
M_PG1_STAT	IRQ mask setting for CH1 power-good status
M_VR_HOT	IRQ mask setting for temp warning status
GPIO1_MODE[3:0]	GPIO1 mode setting
GPIO2_MODE[3:0]	GPIO2 mode setting
GPIO1_OBUF	GPIO1 output buffer select
GPIO2_OBUF	GPIO2 output buffer select
GPIO1_TRIG[1:0]	GPIO1 input trigger select
GPIO1_POL	GPIO1 polarity select
GPIO1_PUPD	GPIO1 pull-up/pull-down enable
GPIO1_DEB[1:0]	GPIO1 input debounce time setting
GPIO1_DEB_RISE	GPIO1 input debounce rising edge enable
GPIO1_DEB_FALL	GPIO1 input debounce falling edge enable
GPIO2_TRIG[1:0]	GPIO2 input trigger select
GPIO2_POL	GPIO2 polarity select
GPIO2_PUPD	GPIO2 pull-up/pull-down enable
GPIO2_DEB[1:0]	GPIO2 input debounce time setting
GPIO2_DEB_RISE	GPIO2 input debounce rising edge enable
GPIO2_DEB_FALL	GPIO2 input debounce falling edge enable

6.3.3 Interrupt

When an event is triggered, the nIRQ interrupt flag is asserted. Trigger conditions and control registers for each interrupt event are listed in [Table 15](#).

Some of these events are categorized as fault events and affect device operation (for example, buck disable), see section [6.2.6](#).

Table 15. Interrupt List

Name	Trigger	IRQ Status Register	IRQ Mask Register	Deglintch Period
Temperature warning (event)	T_J rising above T_{WARN}	E_TEMP_WARN	M_TEMP_WARN	0 s
Temperature critical (event)	T_J rising above T_{CRIT}	E_TEMP_CRIT	M_TEMP_CRIT	0 s
System good (event)	Buck1 power-good event	E_SG	M_SG	0s
Buck1 power-good (event)	Buck1 V_{OUT} is in power-good voltage range (not under- or over-voltage)	E_PG1	M_PG1	0 s
Buck1 over-voltage (event)	Buck1 V_{OUT} rising above over-voltage threshold (target voltage + 150 mV)	E_OV1	M_OV1	Rise: 8 μ s Fall: 8 μ s
Buck1 under-voltage (event)	Buck1 V_{OUT} falling below under-voltage threshold (target voltage - $V_{TH_PG_FALL}$)	E_UV1	M_UV1	0 s
Buck1 over-current (event)	Buck1 current rising above over-current threshold	E_OC1	M_OC1	0 s
Buck1 power-good (status) (Note 1)	Buck1 V_{OUT} is in power-good voltage range (not under- or over-voltage)	PG1	M_PG1_STAT (Note 2)	0 s
System good (status) (Note 1)	Buck1 power-good is active	SG	S_PG_STAT (Note 2)	0 s
Temperature warning (status) (Note 1)	T_J above T_{WARN}	TEMP_WARN	M_VR_HOT (Note 2)	0 s
GPIO0 change (event)	Detect GPIO0 change for active trigger selected by GPIO0_TRIG register	E_GPIO0	M_GPIO0	100 μ s, 1 ms, or 10 ms 100 ms
GPIO1 change (event)	Detect GPIO1 change for active trigger selected by GPIO1_TRIG register	E_GPIO1	M_GPIO1	
GPIO2 change (event)	Detect GPIO2 change for active trigger selected by GPIO2_TRIG register	E_GPIO2	M_GPIO2	

Note 1 Interrupt outputs the status as is. I²C write is not required for interrupt clear

Note 2 Note 2 OTP load value defined by CONF pin setting (if CONF pin enabled).

[Table 16](#) and [Table 17](#) show the interrupt registers' structure. See section [6.3.2.3](#) for bitfield descriptions.

Table 16. Interrupt Registers Except for Power-Good Status

Register	Description
E_<name>	Read-only interrupt event register 0: No interrupt 1: Interrupt occurred Cleared after being written to I²C. Set until IRQ is removed.
M_<name>	Interrupt mask register 0: Not masked 1: Masked. No IRQ signal sent. Event register (E_<name>) is updated.

Table 17. Interrupt Registers for Power-Good and Temperature Warning Status

Register	Description
PG1	Buck1 power-good status. Asserted as long as Buck1 output voltage is in range (under-voltage threshold < buck output voltage < over-voltage threshold) 0: Not power-good 1: Power-good
M_PG1_STAT	Power-good status interrupt mask register 0: Not masked 1: Masked. No IRQ signal sent. Power-good status register (PG1) is updated
TEMP_WARN	Asserted as long as the temperature warning threshold (T_{WARN}) is reached 0: Junction temperature is below T_{WARN} 1: Junction temperature is above T_{WARN}
M_VR_HOT	Temperature warning status (TEMP_WARN) interrupt mask register 0: Not masked 1: Masked. No IRQ signal sent. Temperature warning status register (TEMP_WARN) is updated

It is possible to route interrupts to a GPIO by setting the bitfield GPIO<x>_MODE = 0xC on the relevant GPIO.

nIRQ's behavior is shown in Figure 8. If GPIO_n_POL = 0, nIRQ will be high under normal operation, when system-good status is high, and pulled low if an event listed in Table 15 occurs.

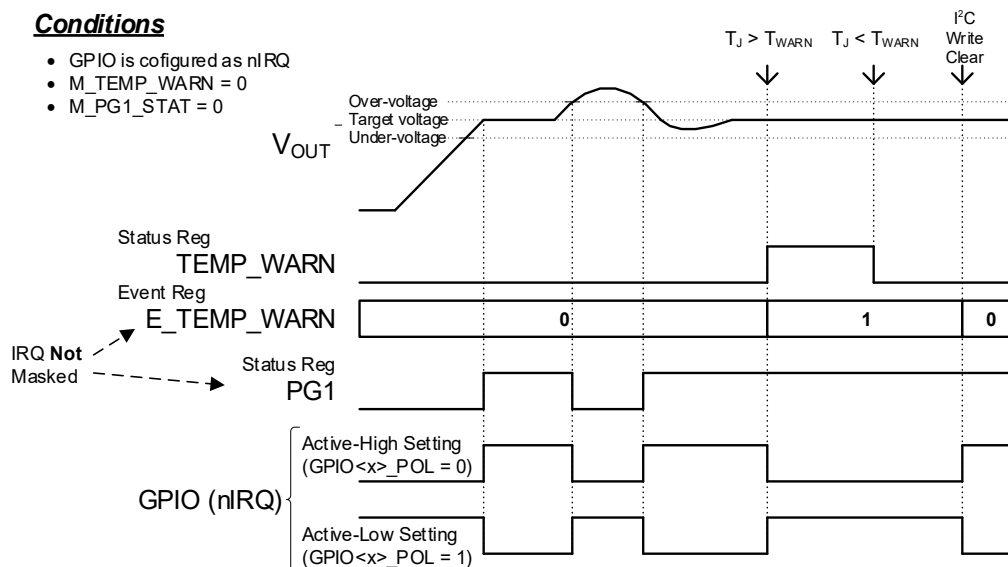


Figure 8. Interrupt Operation Example

6.4 I²C Communication

All features of DA9142-A can be controlled with the I²C interface, which is enabled or disabled as an OTP setting.

I ² C	Description
Disabled	SCL/GPIO3 and SDA/GPIO4 pins should be used as GPO
Enabled	SCL/GPIO3 and SDA/GPIO4 pins are used as I ² C clock input and I ² C data input/output.

GPIO3 functions as the I²C clock (SCL) and GPIO4 carries all the power manager bidirectional I²C data (SDA). The I²C interface is open drain supporting multiple devices on a single line. The bus lines have to be pulled high by external pull-up resistors (2 kΩ to 20 kΩ). The standard frequency of the I²C bus is 1 MHz in fast-mode plus (FM+), 400 kHz in fast-mode, or 100 kHz in standard mode.

6.4.1 I²C Protocol

All data is transmitted across the I²C bus in eight-bit groups. To send a bit, the SDA line is driven towards the intended state while the SCL is low (a low SDA indicates a zero bit). Once the SDA has settled, the SCL line is brought high and then low. This pulse on SCL clocks the SDA bit into the receiver's shift register.

A two-byte serial protocol is used containing one byte for address and one byte for data. Data and address transfer are transmitted MSB first for both read and write operations. All transmissions begin with the START condition from the master while the bus is in idle state (the bus is free). It is initiated by a high to low transition on the SDA line while the SCL is in the high state (a STOP condition is indicated by a low to high transition on the SDA line while the SCL is in the high state).



Figure 9. I²C START and STOP Condition Timing

The I²C bus is monitored for a valid slave address whenever the interface is enabled. It responds immediately when it receives its own slave address. The acknowledge is done by pulling the SDA line low during the following clock cycle (white blocks marked with A in Figure 10 and Figure 11).

The protocol for a register write from master to slave consists of a START condition, a slave address with read/write bit, and the eight-bit register address followed by eight bits of data, terminated by a STOP condition. DA9142-A responds to all bytes with acknowledge (A), see Figure 10.

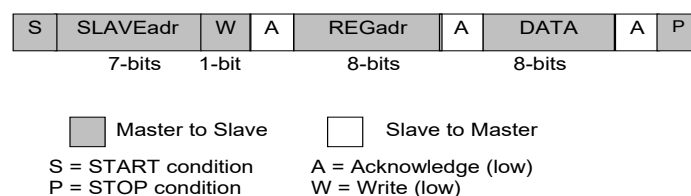
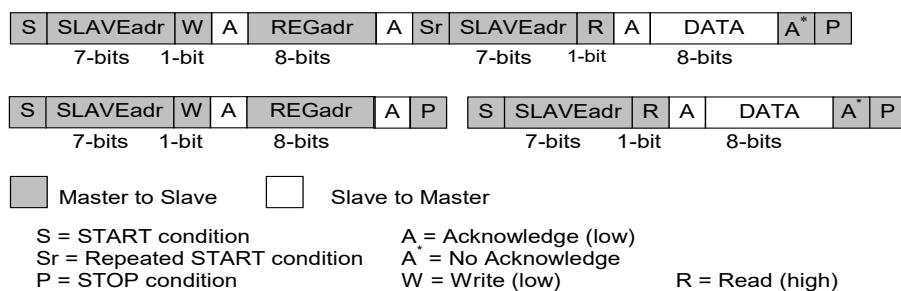


Figure 10. I²C Byte Write (SDA Line)

When the host reads data from a register it first has to write to DA9142-A with the target register address and then read from DA9142-A with a repeated START, or alternatively a second START, condition. After receiving the data, the host sends no acknowledge (A*) and terminates the transmission with a STOP condition, see Figure 11.

Default I²C address is 0xD4 (0x6A excluding the R/W bit). It is possible to change this address by writing the new address to the register SYS_CFG_SLVADDR, see Table 41.

Figure 11. I²C Byte Read (SDA Line) Examples

7. Register Definitions

7.1 Register Map

Table 18: Register Map

Addr	Register	7	6	5	4	3	2	1	0
System Module									
0x01	SYS_STATUS_0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved 0	TEMP_CRIT	TEMP_WARN
0x02	SYS_STATUS_1	Reserved	Reserved	Reserved	Reserved	PG1	OV1	UV1	OC1
0x03	SYS_STATUS_2	Reserved	Reserved	Reserved	Reserved	Reserved	GPIO2	GPIO1	GPIO0
0x04	SYS_EVENT_0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved 0	E_TEMP_CRIT	E_TEMP_WARN
0x05	SYS_EVENT_1	Reserved	Reserved	Reserved	Reserved	E_PG1	E_OV1	E_UV1	E_OC1
0x06	SYS_EVENT_2	Reserved	Reserved	Reserved	Reserved	Reserved	E_GPIO2	E_GPIO1	E_GPIO0
0x07	SYS_MASK_0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved 1	M_TEMP_CRIT	M_TEMP_WARN
0x08	SYS_MASK_1	Reserved	Reserved	Reserved	Reserved	M_PG1	M_OV1	M_UV1	M_OC1
0x09	SYS_MASK_2	Reserved	Reserved	Reserved	Reserved	Reserved	M_GPIO2	M_GPIO1	M_GPIO0
0x0A	SYS_MASK_3	Reserved	Reserved	Reserved	Reserved	M_VR_HOT	Reserved 1	Reserved	M_PG1_STAT
0x0B	SYS_CONFIG_0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
0x0D	SYS_CONFIG_2	Reserved	OC_LATCHOFF<1:0>		OC_DVC_MASK	PG_DVC_MASK<1:0>		Reserved	Reserved
0x0E	SYS_CONFIG_3	Reserved	OSC_TUNE<2:0>			Reserved	Reserved	I2C_TIMEOUT	Reserved 0
0x10	SYS_GPIO0_0	Reserved	Reserved	Reserved	GPIO0_MODE<3:0>				GPIO0_OBUF
0x11	SYS_GPIO0_1	GPIO0_DEB_FALL	GPIO0_DEB_RISE	GPIO0_DEB<1:0>		GPIO0_PUPD	GPIO0_POL	GPIO0_TRIG<1:0>	
0x12	SYS_GPIO1_0	Reserved	Reserved	Reserved	GPIO1_MODE<3:0>				GPIO1_OBUF
0x13	SYS_GPIO1_1	GPIO1_DEB_FALL	GPIO1_DEB_RISE	GPIO1_DEB<1:0>		GPIO1_PUPD	GPIO1_POL	GPIO1_TRIG<1:0>	
0x14	SYS_GPIO2_0	Reserved	Reserved	Reserved	GPIO2_MODE<3:0>				GPIO2_OBUF
0x15	SYS_GPIO2_1	GPIO2_DEB_FALL	GPIO2_DEB_RISE	GPIO2_DEB<1:0>		GPIO2_PUPD	GPIO2_POL	GPIO2_TRIG<1:0>	
0x16	SYS_GPIO3_0	Reserved	Reserved	Reserved	GPIO3_MODE<3:0>				GPIO3_OBUF
0x17	SYS_GPIO3_1	GPIO3_DEB_FALL	GPIO3_DEB_RISE	GPIO3_DEB<1:0>		GPIO3_PUPD	GPIO3_POL	GPIO3_TRIG<1:0>	
0x18	SYS_GPIO4_0	Reserved	Reserved	Reserved	GPIO4_MODE<3:0>				GPIO4_OBUF
0x19	SYS_GPIO4_1	GPIO4_DEB_FALL	GPIO4_DEB_RISE	GPIO4_DEB<1:0>		GPIO4_PUPD	GPIO4_POL	GPIO4_TRIG<1:0>	

DA9142-A Datasheet

Addr	Register	7	6	5	4	3	2	1	0
Buck Control									
Buck1									
0x20	BUCK_BUCK1_0	Reserved	CH1_SR_DVC_DWN<2:0>			CH1_SR_DVC_UP<2:0>			CH1_EN
0x21	BUCK_BUCK1_1	Reserved	CH1_SR_SHDN<2:0>			CH1_SR_STARTUP<2:0>			CH1_PD_DIS
0x22	BUCK_BUCK1_2	Reserved	Reserved	Reserved	Reserved	CH1_ILIM<3:0>			
0x23	BUCK_BUCK1_3	CH1_VMAX<7:0>							
0x24	BUCK_BUCK1_4	Reserved	Reserved	Reserved	CH1_VSEL	CH1_B_MODE<1:0>		CH1_A_MODE<1:0>	
0x25	BUCK_BUCK1_5	CH1_A_VOUT<7:0>							
0x26	BUCK_BUCK1_6	CH1_B_VOUT<7:0>							
0x27	BUCK_BUCK1_7	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	CH1_RIPPLE_CANCEL<1:0>	
OTP Control									
Serialization									
0x48	OTP_DEVICE_ID	DEV_ID<7:0>							
0x49	OTP_VARIANT_ID	MRC<3:0>				VRC<3:0>			
0x4A	OTP_CUSTOMER_ID	CUST_ID<7:0>							
0x4B	OTP_CONFIG_ID	CONFIG_REV<7:0>							

7.2 Register Descriptions

7.2.1 System

Table 19: SYS_STATUS_0 (0x01)

Bit	Type	Field Name	Description
[1]	R	TEMP_CRIT	Asserted when the thermal shutdown threshold is reached
[0]	R	TEMP_WARN	Asserted when the thermal warning threshold is reached

Table 20: SYS_STATUS_1 (0x02)

Bit	Type	Field Name	Description
[3]	R	PG1	Asserted when the buck output voltage is in range
[2]	R	OV1	Asserted when the buck exceeds the over-voltage threshold
[1]	R	UV1	Asserted when the buck exceeds the under-voltage threshold
[0]	R	OC1	Asserted when the buck exceeds the over-current threshold

Table 21: SYS_STATUS_2 (0x03)

Bit	Type	Field Name	Description
[2]	R	GPIO2	GPIO2 input readback status - asserted if the input on GPIO is seen as logic high
[1]	R	GPIO1	GPIO1 input readback status - asserted if the input on GPIO is seen as logic high
[0]	R	GPIO0	GPIO0 input readback status - asserted if the input on GPIO is seen as logic high

Table 22: SYS_EVENT_0 (0x04)

Bit	Type	Field Name	Description
[1]	RW1C	E_TEMP_CRIT	An over-temperature event has occurred. Write 0x1 to reset this bit to 0x0 when the event source has been released.
[0]	RW1C	E_TEMP_WARN	A temperature warning event has occurred. Write 0x1 to reset this bit to 0x0 when the event source has been released.

Table 23: SYS_EVENT_1 (0x05)

Bit	Type	Field Name	Description
[3]	RW1C	E_PG1	PG1 caused event. Write 0x1 to reset this bit to 0x0 when the event source has been released.
[2]	RW1C	E_OV1	OV1 caused event. Write 0x1 to reset this bit to 0x0 when the event source has been released.
[1]	RW1C	E_UV1	UV1 caused event. Write 0x1 to reset this bit to 0x0 when the event source has been released.
[0]	RW1C	E_OC1	OC1 caused event. Write 0x1 to reset this bit to 0x0 when the event source has been released.

Table 24: SYS_EVENT_2 (0x06)

Bit	Type	Field Name	Description
[2]	RW1C	E_GPIO2	GPIO2 caused event. Write 0x1 to reset this bit to 0x0 when the event source has been released.

Bit	Type	Field Name	Description
[1]	RW1C	E_GPIO1	GPIO1 caused event. Write 0x1 to reset this bit to 0x0 when the event source has been released.
[0]	RW1C	E_GPIO0	GPIO0 caused event. Write 0x1 to reset this bit to 0x0 when the event source has been released.

Table 25: SYS_MASK_0 (0x07)

Bit	Type	Field Name	Description
[1]	RW	M_TEMP_CRIT	Thermal shutdown can cause an interrupt. Write 0x1 to mask this cause of interrupt.
[0]	RW	M_TEMP_WARN	Temperature warning can cause an interrupt. Write 0x1 to mask this cause of interrupt.

Table 26: SYS_MASK_1 (0x08)

Bit	Type	Field Name	Description
[3]	RW	M_PG1	PG1 event can cause an interrupt. Write 0x1 to mask this cause of interrupt.
[2]	RW	M_OV1	OV1 event can cause an interrupt. Write 0x1 to mask this cause of interrupt.
[1]	RW	M_UV1	UV1 event can cause an interrupt. Write 0x1 to mask this cause of interrupt.
[0]	RW	M_OC1	OC1 event can cause an interrupt. Write 0x1 to mask this cause of interrupt.

Table 27: SYS_MASK_2 (0x09)

Bit	Type	Field Name	Description
[2]	RW	M_GPIO2	GPIO2 event can cause an interrupt. Write 0x1 to mask this cause of interrupt.
[1]	RW	M_GPIO1	GPIO1 event can cause an interrupt. Write 0x1 to mask this cause of interrupt.
[0]	RW	M_GPIO0	GPIO0 event can cause an interrupt. Write 0x1 to mask this cause of interrupt.

Table 28: SYS_MASK_3 (0x0A)

Bit	Type	Field Name	Description
[3]	RW	M_VR_HOT	Temperature warning status IRQ mask. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting)
[0]	RW	M_PG1_STAT	PG1 status IRQ mask. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting)

Table 29: SYS_CONFIG_2 (0x0D)

Bit	Type	Field Name	Description						
[6:5]	RW	OC_LATCHOFF	Over-current latch-off time (Debounce duration). Buck shuts down after over-current persists for 8 μs, 1 ms or 3 ms unless setting is disabled setting. An IRQ is generated unless masked. <table><thead><tr><th>Value</th><th>Description</th></tr></thead><tbody><tr><td>0x0</td><td>Latch off disable</td></tr><tr><td>0x1</td><td>Latch off after 8 μs</td></tr></tbody></table>	Value	Description	0x0	Latch off disable	0x1	Latch off after 8 μs
Value	Description								
0x0	Latch off disable								
0x1	Latch off after 8 μs								

Bit	Type	Field Name	Description										
			0x2 Latch off after 1 ms 0x3 Latch off after 3 ms										
[4]	RW	OC_DVC_MASK	Over-current event mask during DVC ramp-up and ramp-down. Write 0x1 to mask over-current during DVC causing IRQ and LATCHOFF.										
[3:2]	RW	PG_DVC_MASK	Power good mask during DVC <table><tr><th>Value</th><th>Description</th></tr><tr><td>0x0</td><td>No mask</td></tr><tr><td>0x1</td><td>Mask as not power good</td></tr><tr><td>0x2</td><td>Mask as power good</td></tr><tr><td>0x3</td><td>Reserved</td></tr></table>	Value	Description	0x0	No mask	0x1	Mask as not power good	0x2	Mask as power good	0x3	Reserved
Value	Description												
0x0	No mask												
0x1	Mask as not power good												
0x2	Mask as power good												
0x3	Reserved												

Table 30: SYS_CONFIG_3 (0x0E)

Bit	Type	Field Name	Description
[6:4]	RW	OSC_TUNE	Tune oscillator frequency, tuned frequency = current frequency + OSC_TUNE * 160 kHz
			Value Description
			0x33
			0x22
			0x11
			0x00
			0x7-1
			0x6-2
			0x5-3
0x4-4			
[1]	RW	I2C_TIMEOUT	Enable automatic reset of 2 wire interface (if SDA stays low for > 50 ms).

Table 31: SYS_GPIO0_0 (0x10)

Bit	Type	Field Name	Description
[4:1]	RW	GPIO0_MODE	GPIO function mode select
			Value Description
			0x0GPIO disable
			0x1EN1 input
			0x2Reserved
			0x3EN1 input
			0x4DVC1 input
			0x5Reserved
			0x6DVC1 input
			0x7RELOAD input
			0x8PG1 output
0x9Low output			

Bit	Type	Field Name	Description
			0xA Low output 0xB PG1 output 0xC nIRQ output 0xD Reserved 0xE Low output 0xF High output
[0]	RW	GPIO0_OBUF	GPIO output buffer select Value Description 0x0 open-drain output 0x1 push-pull output

Table 32: SYS_GPIO0_1 (0x11)

Bit	Type	Field Name	Description
[7]	RW	GPIO0_DEB_FALL	GPI debounce falling edge
[6]	RW	GPIO0_DEB_RISE	GPI debounce rising edge
[5:4]	RW	GPIO0_DEB	GPI debounce time Value Description 0x0 100 μ s debounce 0x1 1 ms debounce 0x2 10 ms debounce 0x3 100 ms debounce
[3]	RW	GPIO0_PUPD	GPIO pull-up/pull-down enable Value Description 0x0 GPI: pull-down disabled, GPO: pull-up to AVDD disabled 0x1 GPI: pull-down enabled, GPO: pull-up to AVDD enabled
[2]	RW	GPIO0_POL	GPIO polarity Value Description 0x0 GPIO is active-high 0x1 GPIO is active-low
[1:0]	RW	GPIO0_TRIG	GPI trigger type Value Description 0x0 Dual-edge triggered 0x1 Positive-edge triggered 0x2 Negative-edge triggered 0x3 Reserved (No trigger)

Table 33: SYS_GPIO1_0 (0x12)

Bit	Type	Field Name	Description																																		
[4:1]	RW	GPIO1_MODE	GPIO function mode select. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) <table><thead><tr><th>Value</th><th>Description</th></tr></thead><tbody><tr><td>0x0</td><td>GPIO disable</td></tr><tr><td>0x1</td><td>EN1 input</td></tr><tr><td>0x2</td><td>Reserved</td></tr><tr><td>0x3</td><td>EN1 input</td></tr><tr><td>0x4</td><td>DVC1 input</td></tr><tr><td>0x5</td><td>Reserved</td></tr><tr><td>0x6</td><td>DVC1 input</td></tr><tr><td>0x7</td><td>RELOAD input</td></tr><tr><td>0x8</td><td>PG1 output</td></tr><tr><td>0x9</td><td>Low output</td></tr><tr><td>0xA</td><td>Low output</td></tr><tr><td>0xB</td><td>PG1 output</td></tr><tr><td>0xC</td><td>nIRQ output</td></tr><tr><td>0xD</td><td>Reserved</td></tr><tr><td>0xE</td><td>Low output</td></tr><tr><td>0xF</td><td>High output</td></tr></tbody></table>	Value	Description	0x0	GPIO disable	0x1	EN1 input	0x2	Reserved	0x3	EN1 input	0x4	DVC1 input	0x5	Reserved	0x6	DVC1 input	0x7	RELOAD input	0x8	PG1 output	0x9	Low output	0xA	Low output	0xB	PG1 output	0xC	nIRQ output	0xD	Reserved	0xE	Low output	0xF	High output
Value	Description																																				
0x0	GPIO disable																																				
0x1	EN1 input																																				
0x2	Reserved																																				
0x3	EN1 input																																				
0x4	DVC1 input																																				
0x5	Reserved																																				
0x6	DVC1 input																																				
0x7	RELOAD input																																				
0x8	PG1 output																																				
0x9	Low output																																				
0xA	Low output																																				
0xB	PG1 output																																				
0xC	nIRQ output																																				
0xD	Reserved																																				
0xE	Low output																																				
0xF	High output																																				
[0]	RW	GPIO1_OBUF	GPIO output buffer select. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting). <table><thead><tr><th>Value</th><th>Description</th></tr></thead><tbody><tr><td>0x0</td><td>open-drain output</td></tr><tr><td>0x1</td><td>push-pull output</td></tr></tbody></table>	Value	Description	0x0	open-drain output	0x1	push-pull output																												
Value	Description																																				
0x0	open-drain output																																				
0x1	push-pull output																																				

Table 34: SYS_GPIO1_1 (0x13)

Bit	Type	Field Name	Description										
[7]	RW	GPIO1_DEB_FALL	GPI debounce falling edge. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting)										
[6]	RW	GPIO1_DEB_RISE	GPI debounce rising edge. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting)										
[5:4]	RW	GPIO1_DEB	GPI debounce time. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) <table><thead><tr><th>Value</th><th>Description</th></tr></thead><tbody><tr><td>0x0</td><td>100 μs debounce</td></tr><tr><td>0x1</td><td>1 ms debounce</td></tr><tr><td>0x2</td><td>10 ms debounce</td></tr><tr><td>0x3</td><td>100 ms debounce</td></tr></tbody></table>	Value	Description	0x0	100 μs debounce	0x1	1 ms debounce	0x2	10 ms debounce	0x3	100 ms debounce
Value	Description												
0x0	100 μs debounce												
0x1	1 ms debounce												
0x2	10 ms debounce												
0x3	100 ms debounce												
[3]	RW	GPIO1_PUPD	GPIO pull-up/pull-down enable. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting)										

Bit	Type	Field Name	Description
			Value Description 0x0 GPI: pull-down disabled, GPO: pull-up to AVDD disabled 0x1 GPI: pull-down enabled, GPO: pull-up to AVDD enabled
[2]	RW	GPIO1_POL	GPIO polarity. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) Value Description 0x0 GPIO is active-high 0x1 GPIO is active-low
[1:0]	RW	GPIO1_TRIG	GPI trigger type. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) Value Description 0x0 Dual-edge triggered 0x1 Positive-edge triggered 0x2 Negative-edge triggered 0x3 Reserved (No trigger)

Table 35: SYS_GPIO2_0 (0x14)

Bit	Type	Field Name	Description
[4:1]	RW	GPIO2_MODE	GPIO function mode select. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) Value Description 0x0 GPIO disable 0x1 EN1 input 0x2 Reserved 0x3 EN1 input 0x4 DVC1 input 0x5 Reserved 0x6 DVC1 input 0x7 RELOAD input 0x8 PG1 output 0x9 Low output 0xA Low output 0xB PG1 output 0xC nIRQ output 0xD Reserved 0xE Low output 0xF High output
[0]	RW	GPIO2_OBUF	GPIO output buffer select. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting)

Bit	Type	Field Name	Description
			Value Description 0x0 open-drain output 0x1 push-pull output

Table 36: SYS_GPIO2_1 (0x15)

Bit	Type	Field Name	Description
[7]	RW	GPIO2_DEB_FALL	GPI debounce falling edge. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting)
[6]	RW	GPIO2_DEB_RISE	GPI debounce rising edge. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting)
[5:4]	RW	GPIO2_DEB	GPI debounce time. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) Value Description 0x0 100 μ s debounce 0x1 1 ms debounce 0x2 10 ms debounce 0x3 100 ms debounce
[3]	RW	GPIO2_PUPD	GPIO pull-up/pull-down enable. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) Value Description 0x0 GPI: pull-down disabled, GPO: pull-up to AVDD disabled 0x1 GPI: pull-down enabled, GPO: pull-up to AVDD enabled
[2]	RW	GPIO2_POL	GPIO polarity. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) Value Description 0x0 GPIO is active-high 0x1 GPIO is active-low
[1:0]	RW	GPIO2_TRIG	GPI trigger type. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) Value Description 0x0 Dual-edge triggered 0x1 Positive-edge triggered 0x2 Negative-edge triggered 0x3 Reserved (No trigger)

Table 37: SYS_GPIO3_0 (0x16)

Bit	Type	Field Name	Description
[4:1]	R	GPIO3_MODE	GPIO function mode select Value Description 0x0 GPIO disable

Bit	Type	Field Name	Description
			0x1 EN1 input 0x2 Reserved 0x3 EN1 input 0x4 DVC1 input 0x5 Reserved 0x6 DVC1 input 0x7 RELOAD input 0x8 PG1 output 0x9 Low output 0xA Low output 0xB PG1 output 0xC nIRQ output 0xD Reserved 0xE Low output 0xF High output
[0]	R	GPIO3_OBUF	GPIO output buffer select Value Description 0x0 open-drain output 0x1 push-pull output

Table 38: SYS_GPIO3_1 (0x17)

Bit	Type	Field Name	Description
[7]	R	GPIO3_DEB_FALL	GPI debounce falling edge
[6]	R	GPIO3_DEB_RISE	GPI debounce rising edge
[5:4]	R	GPIO3_DEB	GPI debounce time Value Description 0x0 100 μ s debounce 0x1 1 ms debounce 0x2 10 ms debounce 0x3 100 ms debounce
[3]	R	GPIO3_PUPD	GPIO pull-up/pull-down enable Value Description 0x0 GPI: pull-down disabled, GPO: pull-up to AVDD disabled 0x1 GPI: pull-down enabled, GPO: pull-up to AVDD enabled
[2]	R	GPIO3_POL	GPIO polarity Value Description 0x0 GPIO is active-high 0x1 GPIO is active-low

Bit	Type	Field Name	Description
[1:0]	R	GPIO3_TRIG	GPI trigger type
			Value Description
			0x0Dual-edge triggered
			0x1Positive-edge triggered
			0x2Negative-edge triggered
			0x3Reserved (No trigger)

Table 39: SYS_GPIO4_0 (0x18)

Bit	Type	Field Name	Description
[4:1]	R	GPIO4_MODE	GPIO function mode select
			Value Description
			0x0GPIO disable
			0x1EN1 input
			0x2Reserved
			0x3EN1 input
			0x4DVC1 input
			0x5Reserved
			0x6DVC1 input
			0x7RELOAD input
			0x8PG1 output
			0x9Low output
			0xALow output
			0xBPG1 output
			0xCnIRQ output
			0xDReserved
			0xELow output
0xFHigh output			
[0]	R	GPIO4_OBUF	GPIO output buffer select
			Value Description
			0x0open-drain output
			0x1push-pull output

Table 40: SYS_GPIO4_1 (0x19)

Bit	Type	Field Name	Description						
[7]	R	GPIO4_DEB_FALL	GPI debounce falling edge						
[6]	R	GPIO4_DEB_RISE	GPI debounce rising edge						
[5:4]	R	GPIO4_DEB	GPI debounce time <table><thead><tr><th>Value</th><th>Description</th></tr></thead><tbody><tr><td>0x0</td><td>100 μs debounce</td></tr><tr><td>0x1</td><td>1 ms debounce</td></tr></tbody></table>	Value	Description	0x0	100 μs debounce	0x1	1 ms debounce
Value	Description								
0x0	100 μs debounce								
0x1	1 ms debounce								

Bit	Type	Field Name	Description
			0x2 10 ms debounce 0x3 100 ms debounce
[3]	R	GPIO4_PUPD	GPIO pull-up/pull-down enable Value Description 0x0 GPI: pull-down disabled, GPO: pull-up to AVDD disabled 0x1 GPI: pull-down enabled, GPO: pull-up to AVDD enabled
[2]	R	GPIO4_POL	GPIO polarity Value Description 0x0 GPIO is active-high 0x1 GPIO is active-low
[1:0]	R	GPIO4_TRIG	GPI trigger type Value Description 0x0 Dual-edge triggered 0x1 Positive-edge triggered 0x2 Negative-edge triggered 0x3 Reserved (No trigger)

Table 41: SYS_CFG_SLVADDR (0xA1)

Bit	Type	Symbol	Description
[6:0]	RW	I2C_SLAVE_ADDR	Slave address of the device.

7.2.2 Buck1

Table 42: BUCK_BUCK1_0 (0x20)

Bit	Type	Field Name	Description
[6:4]	RW	CH1_SR_DVC_DWN	Voltage slew-rate for DVC ramp-down Value Description 0x0 10 mV / 8 μ s 0x1 10 mV / 4 μ s 0x2 10 mV / 2 μ s 0x3 10 mV / 1 μ s 0x4 20 mV / 1 μ s 0x5 Reserved 0x6 Reserved 0x7 Reserved
[3:1]	RW	CH1_SR_DVC_UP	Voltage slew-rate for DVC ramp-up Value Description 0x0 10 mV / 8 μ s 0x1 10 mV / 4 μ s 0x2 10 mV / 2 μ s

Bit	Type	Field Name	Description
			0x3 10 mV / 1 μ s 0x4 20 mV / 1 μ s 0x5 40 mV / 1 μ s 0x6 Reserved 0x7 Reserved
[0]	RW	CH1_EN	Channel enable. Write 0x1 to enable the buck. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting)

Table 43: BUCK_BUCK1_1 (0x21)

Bit	Type	Field Name	Description
[6:4]	RW	CH1_SR_SHDN	Voltage slew-rate during shut-down Value Description 0x0 10 mV / 8 μ s 0x1 10 mV / 4 μ s 0x2 10 mV / 2 μ s 0x3 10 mV / 1 μ s 0x4 20 mV / 1 μ s 0x5 Reserved 0x6 Reserved 0x7 Immediate power-down
[3:1]	RW	CH1_SR_STARTUP	Voltage slew-rate during start-up Value Description 0x0 10 mV / 8 μ s 0x1 10 mV / 4 μ s 0x2 10 mV / 2 μ s 0x3 10 mV / 1 μ s 0x4 20 mV / 1 μ s 0x5 40 mV / 1 μ s 0x6 Reserved 0x7 Reserved
[0]	RW	CH1_PD_DIS	LX Pull down while BUCK is off. Write 0x1 to disable this function.

Table 44: BUCK_BUCK1_2 (0x22)

Bit	Type	Field Name	Description
[3:0]	RW	CH1_ILIM	Select OCP threshold (A) Value Description 0x0 Reserved 0x1 6.5 0x2 7.5

Bit	Type	Field Name	Description
			0x3 8.5
			0x4 9.5
			0x5 10.5
			0x6 11.5
			0x7 12.5
			0x8 13.5
			0x9 14.5
			0xA 15.5
			0xB 16.5
			0xC 17.5
			0xD 18.5
			0xE 19.5
			0xF Disable

Table 45: BUCK_BUCK1_3 (0x23)

Bit	Type	Field Name	Description																												
[7:0]	R	CH1_VMAX	VOUT max setting (V): From 0.50 V (0x32) to 1.30 V (0x82) in steps of 10 mV This is a read-only register. <table><thead><tr><th>Value</th><th>Description</th></tr></thead><tbody><tr><td>0x00</td><td>Reserved</td></tr><tr><td>0x31</td><td>Reserved</td></tr><tr><td>0x32</td><td>0.5</td></tr><tr><td>0x33</td><td>0.51</td></tr><tr><td>...</td><td>+0.01 steps</td></tr><tr><td>0x63</td><td>0.99</td></tr><tr><td>0x64</td><td>1</td></tr><tr><td>0x65</td><td>1.01</td></tr><tr><td>...</td><td>+0.01 steps</td></tr><tr><td>0x81</td><td>1.29</td></tr><tr><td>0x82</td><td>1.3</td></tr><tr><td>0x83</td><td>Reserved</td></tr><tr><td>0xFF</td><td>Reserved</td></tr></tbody></table>	Value	Description	0x00	Reserved	0x31	Reserved	0x32	0.5	0x33	0.51	...	+0.01 steps	0x63	0.99	0x64	1	0x65	1.01	...	+0.01 steps	0x81	1.29	0x82	1.3	0x83	Reserved	0xFF	Reserved
Value	Description																														
0x00	Reserved																														
0x31	Reserved																														
0x32	0.5																														
0x33	0.51																														
...	+0.01 steps																														
0x63	0.99																														
0x64	1																														
0x65	1.01																														
...	+0.01 steps																														
0x81	1.29																														
0x82	1.3																														
0x83	Reserved																														
0xFF	Reserved																														

Table 46: BUCK_BUCK1_4 (0x24)

Bit	Type	Field Name	Description
[4]	RW	CH1_VSEL	Output voltage and operation selection: 0: A, 1: B. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting)
[3:2]	RW	CH1_B_MODE	Operation mode selection. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting)

Bit	Type	Field Name	Description
			Value Description 0x0 Force PFM operation 0x1 Force PWM operation (full phase) 0x2 Force PWM operation (with phase shedding) 0x3 Auto mode
[1:0]	RW	CH1_A_MODE	Operation mode selection. Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) Value Description 0x0 Force PFM operation 0x1 Force PWM operation (full phase) 0x2 Force PWM operation (with phase shedding) 0x3 Auto mode

Table 47: BUCK_BUCK1_5 (0x25)

Bit	Type	Field Name	Description
[7:0]	RW	CH1_A_VOUT	Output voltage setting A: Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) From 0.50 V (0x32) to 1.30 V (0x82) in steps of 10 mV Value Description 0x00 Reserved 0x31 Reserved 0x32 0.5 0x33 0.51 ... +0.01 steps 0x63 0.99 0x64 1 0x65 1.01 ... +0.01 steps 0x81 1.29 0x82 1.3 0x83 Reserved 0xFF Reserved

Table 48: BUCK_BUCK1_6 (0x26)

Bit	Type	Field Name	Description
[7:0]	RW	CH1_B_VOUT	Output voltage setting B: Initial value is determined by CONF pin setting during start-up and if the CONF pin is enabled (OTP setting) From 0.50 V (0x32) to 1.30 V (0x82) in steps of 10 mV (default 1.0 V) Value Description 0x00 Reserved

Bit	Type	Field Name	Description
			0x31 Reserved
			0x32 0.5
			0x33 0.51
			... +0.01 steps
			0x63 0.99
			0x64 1
			0x65 1.01
			... +0.01 steps
			0x81 1.29
			0x82 1.3
			0x83 Reserved
			0xFF Reserved

Table 49: BUCK_BUCK1_7 (0x27)

Bit	Type	Field Name	Description
[1:0]	RW	CH1_RIPPLE_CANCEL	Ripple cancel control
			Value Description
			0x0No ripple cancel
			0x1Small ripple cancel
			0x2Mid ripple cancel
			0x3Large ripple cancel

7.2.3 OTP Control

7.2.3.1 Serialization

Table 50: OTP_DEVICE_ID (0x48)

Bit	Type	Field Name	Description
[7:0]	R	DEV_ID	Device ID; hard-coded or metal-programmed

Table 51: OTP_VARIANT_ID (0x49)

Bit	Type	Field Name	Description
[7:4]	R	MRC	Mask Revision Code
[3:0]	R	VRC	Chip Variant Code; e.g. package variants.

Table 52: OTP_CUSTOMER_ID (0x4A)

Bit	Type	Field Name	Description
[7:0]	R	CUST_ID	Customer ID

Table 53: OTP_CONFIG_ID (0x4B)

Bit	Type	Field Name	Description
[7:0]	R	CONFIG_REV	OTP settings revision

8. Moisture Sensitivity Level

The Moisture Sensitivity Level (MSL) is an indicator for the maximum allowable time period (floor lifetime) in which a moisture sensitive plastic device, once removed from the dry bag, can be exposed to an environment with a specified maximum temperature and a maximum relative humidity before the solder reflow process. The MSL classification is defined in [Table 54](#).

For detailed information on MSL levels, refer to the IPC/JEDEC standard J-STD-020, which can be downloaded from <http://www.jedec.org>.

The DA9142-A package is qualified for MSL 3.

Table 54. MSL Classification

MSL Level	Floor Lifetime	Conditions
MSL 4	72 hours	30 °C/60% RH
MSL 3	168 hours	30 °C/60% RH
MSL 2A	4 weeks	30 °C/60% RH
MSL 2	1 year	30 °C/60% RH
MSL 1	Unlimited	30 °C/85% RH

8.1 Soldering Information

Refer to the IPC/JEDEC standard J-STD-020 for relevant soldering information. This document can be downloaded from <http://www.jedec.org>.

9. Package Outline Drawings

9.1 Package Outline

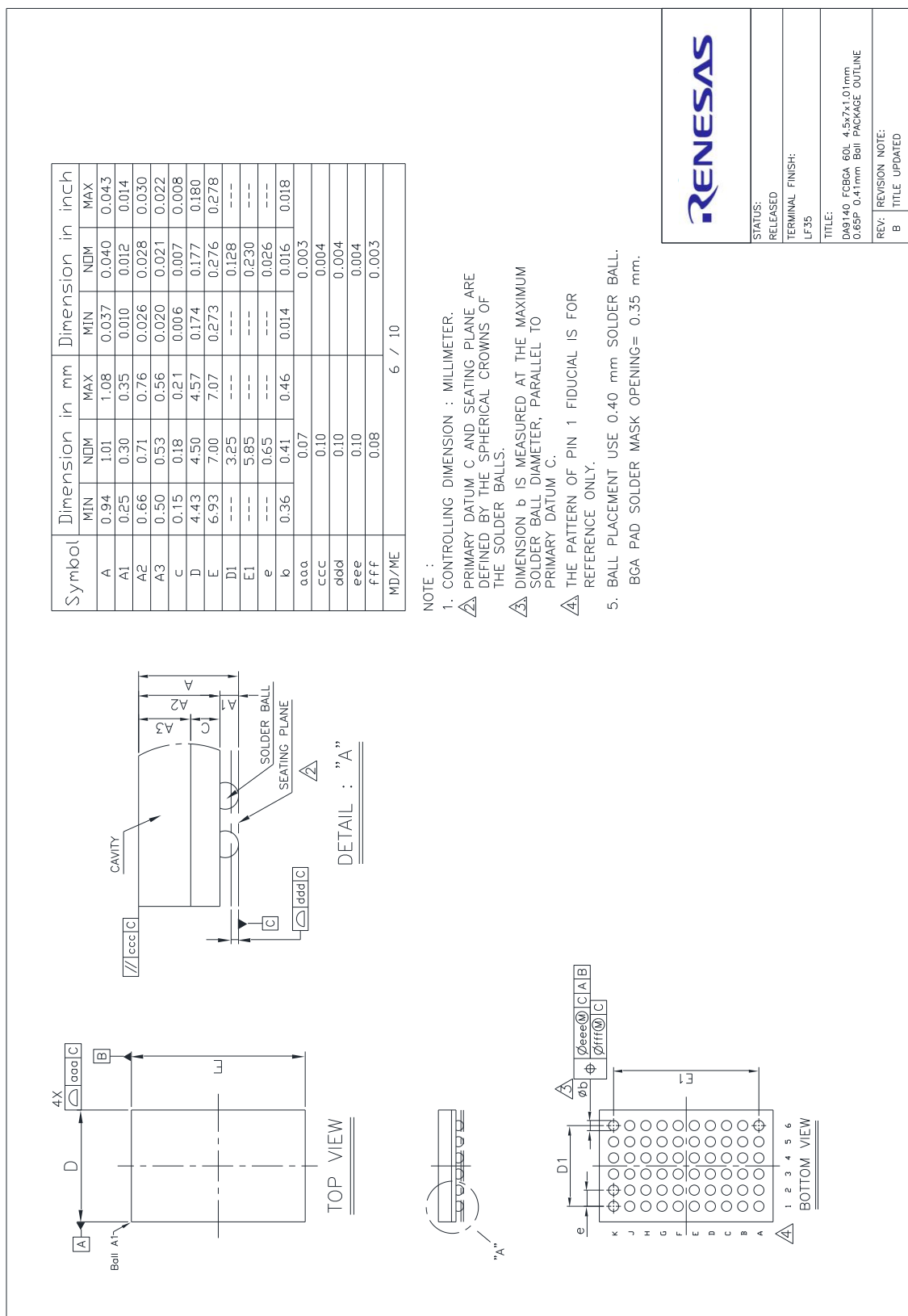


Figure 12. Package Outline Drawing

9.2 Package Marking

Package Marking		
A1 Corner >	Marking Content	Format
1st	•	Pin 1 ID
2nd		
3rd		
4th		Part No./Option
5th		OTP
6th		Date Code
-A optionally indicate the Automotive test options.		
xx identifies the OTP Variant		
Date Code Format: yy = Year, ww = Week, zzzz = Traceability		

Figure 13. Chip Marking Details

10. Ordering Information

The ordering number consists of the part number followed by a suffix indicating the packing method. For details and availability, please consult your Renesas [local sales representative](#).

Table 55. Ordering Information for Consumer/Industrial Applications

Part Number	Package Description	Size (mm)	Carrier Type	Pack Quantity
DA9142-xxF71	60 FCBGA	4.5 x 7 x 1.01 0.65 mm pitch	Tray	364
DA9142-xxF72	60 FCBGA	4.5 x 7 x 1.01 0.65 mm pitch	Reel	2600

Table 56. Ordering Information for Automotive Applications

Part Number	Package Description	Size (mm)	Carrier Type	Pack Quantity
DA9142-xxF71-A	60 FCBGA	4.5 x 7 x 1.01 0.65 mm pitch	Tray	364
DA9142-xxF72-A	60 FCBGA	4.5 x 7 x 1.01 0.65 mm pitch	Reel	2600

10.1 Variants Ordering Information

DA9142-A supports delivery of variants indicated by xx in the part number above, where xx is replaced with the actual variant number. Please contact your Renesas [local sales representative](#) to discuss requirements.

11. Application Information

11.1 Capacitor Selection

Ceramic capacitors are used as bypass capacitors at all VDD and output rails. When selecting a capacitor, especially for types with high capacitance at smallest physical dimension, the DC bias characteristic has to be taken into account.

Table 57: Recommended Automotive-Grade Capacitor Types

Application	Value (μF)	Size	Temp. Char.	Tol. (%)	V-Rate (V)	Type
VOUT output bypass	22	1206	X7R	±20	6.3	Murata GCM31CR70J226ME23L
PVDDx bypass	10	0805	X7S	±10	16	Murata GCM21BC71C106KE36L
PVDDx bypass for VSYS < 4V	10	0603	X7T	±20	6.3	Murata GCM188D70J106ME36L
AVDD bypass	1	0805	X7R	±10	50	Murata GCM21BR71H105KA03L

11.2 Inductor Selection

Inductors should be selected based on the following parameters:

- Rated maximum current and ISAT
ISAT specifies the maximum current at which the inductance drops by 30% of the nominal value, and IMAX is defined by the maximum power dissipation and is applied to the effective current at 40 °C temperature rise.
- DC resistance
Critical for the converter efficiency and should therefore be minimized.

Table 58: Recommended Inductor Types

Value (nH)	Size (mm)	IMAX (DC) (A)	ISAT (A)	Tol. (%)	DC Resistance (mΩ)	Type
112	3.2 x 2.5 x 2.5	20	31	20	1.9	TDK CLT3225AR11MI3
110	4.0 x 4.0 x 2.1	29	29	20	1.4	Coilcraft XGL4020-111MEC
100	5.3 x 5.1 x 3.0	18.3	37.1	20	2.7	TDK SPM5030VT-R10M-D

12. Layout Guidelines

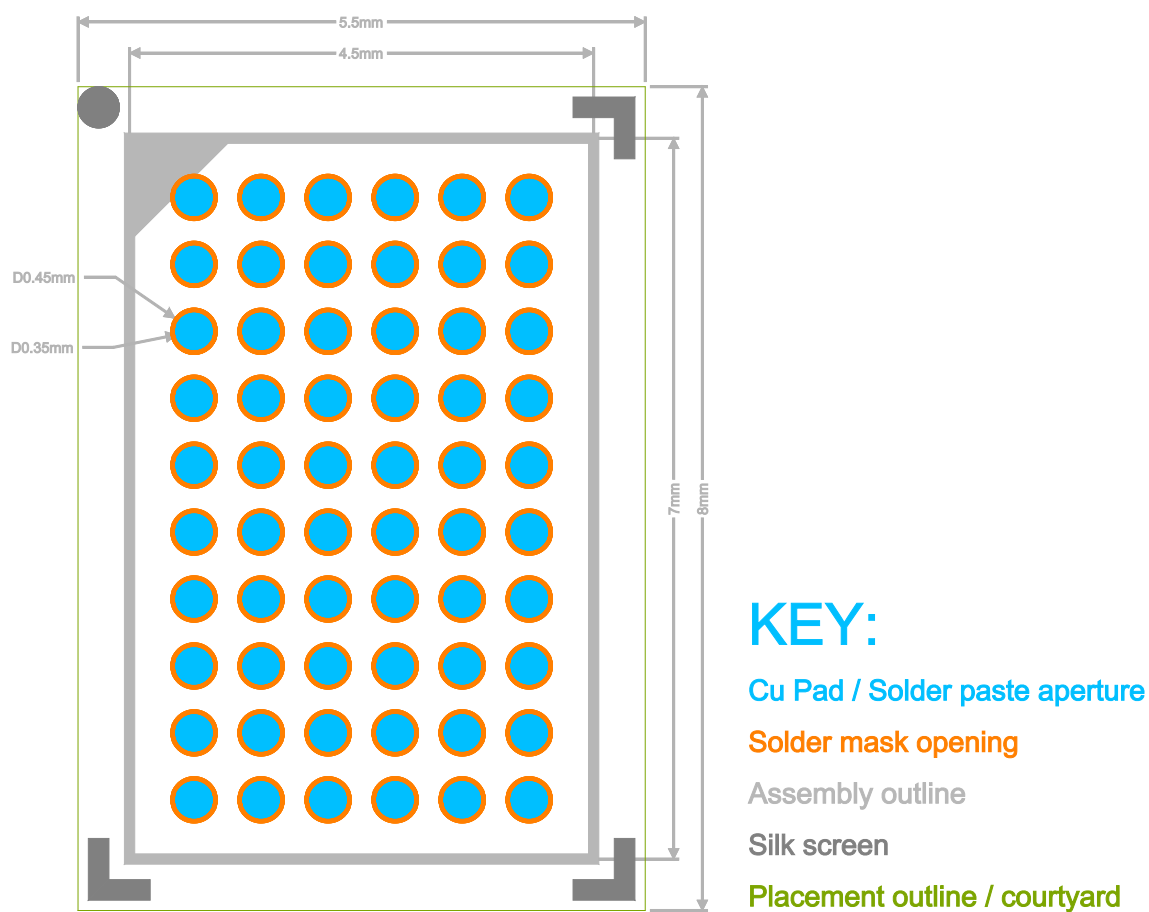


Figure 14. DA9142-A Footprint

RoHS Compliance

Renesas Electronics' suppliers certify that its products are in compliance with the requirements of Directive 2011/65/EU of the European Parliament on the restriction of the use of certain hazardous substances in electrical and electronic equipment. RoHS certificates from our suppliers are available on request.

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(Disclaimer Rev.5.0-1)

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